TDF series for Wireless LAN / 适用无线LAN的TDF系列

SELECTION GUIDE FOR STANDARD DEVICES / 标准设备选择指南

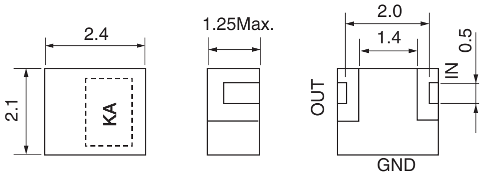
- The Part Numbers shown in the table below are standard devices, which are readily available. TOKO will design and manufacture modified and custom devices with specific characteristics to meet your requirements.
  If you do not find the device for your application in this catalog, please contact our sales or representative office.
- RoHS compliant.

- 下表中所示部品号为标准设备，可随时提供。为满足您的需求，东光也设计和生产有特定性能的改装与自定义设备。
  如果目录中没有您所需要的设备，请与我们的销售处或代表处联系。
- 符合RoHS指令。

东光部品号	中心频率	带宽	最大插入损耗	BW中的最大V.S.W.R.（电压驻波比）	最小选择度	尺寸 宽×长×高	应用	个/卷
TOKO Part Number	**Center Frequency (MHz)**	**Bandwidth (MHz)**	**Insertion Loss (dB) Max.**	**V.S.W.R. in BW Max.**	**Selectivity (dB) Min. (MHz)**	**Dimension (mm) W × L × T (Max.)**	**Application**	**Pcs/Reel**
TDF2A-2450T-10A	2450.0	Fo ± 50.0	2.00	2.00	20, 16 (Fo – 280, + 280)	5.7 × 5.1 × 2.25	2.4G-LAN	2000
TDFM1A-2450T-10A	2450.0	Fo ± 50.0	2.00	2.00	20, 16 (Fo – 280, Fo + 280)	4.5 × 5.2 × 2.0	2.4G-LAN	2000
TDFM1B-2450T-10A	2450.0	Fo ± 50.0	2.30	2.00	35, 30 (Fo – 430, + 350)	6.5 × 5.1 × 2.0	2.4G-LAN	1500
TDFM1C-2450T-10A	2450.0	Fo ± 50.0	3.00	2.00	21, 32 (Fo ± 150, – 200)	9.0 × 5.15 × 2.0	2.4G-LAN	1500
TDFS8A-2450T-13A	2450.0	Fo ± 50.0	2.00	2.00	40 (Fo – 500)	3.2 × 3.0 × 1.8	2.4G-LAN	2000
TDFU2A-2450T-10A	2450.0	Fo ± 50.0	1.50	2.00	30 (1910~1990)	2.0 × 2.85 × 1.25	2.4G-LAN	3000
TDF2A-2484E-11A	2484.0	Fo ± 13.0	3.00	1.60	35, 30 (Fo ± 350, ± 700)	5.7 × 5.1 × 2.25	2.4G-LAN	2000
TDF2A-2484E-12A	2484.0	Fo ± 13.0	2.00	1.60	25, 30 (Fo ± 350, ± 700)	5.7 × 5.1 × 2.25	2.4G-LAN	2000
TDFM1A-2484E-10A	2484.0	Fo ± 13.0	2.00	2.00	25, 30 (Fo ± 350, ± 700)	4.5 × 5.1 × 2.0	2.4G-LAN	2000
TDFM1A-2484E-11A	2484.0	Fo ± 13.0	3.00	2.00	35, 30 (Fo ± 350, ± 700)	4.5 × 5.2 × 2.0	2.4G-LAN	2000
TDFM1B-2546S-10A	2546.0	Fo ± 46.5	1.80	2.00	44, 40 (Fo ± 412.4, ± 868.5)	6.5 × 4.05 × 1.90	MMDS	2000
TDFM1B-2639S-10A	2639.5	Fo ± 46.5	1.50	2.00	33, 35 (Fo ± 410.5, ± 866.5)	6.5 × 4.75 × 1.90	MMDS	2000
TDFS1C-3449T-10A	3449.75	Fo ± 50.25	1.50	2.00	40, 45 (Fo – 862, – 406)	6.5 × 4.4 × 2.0	Wi MAX	2000
TDFM2A-3549T-10A	3549.75	Fo ± 50.25	1.40	2.00	31, 33 (Fo – 882, – 406)	4.5 × 4.5 × 2.25	Wi MAX	2000
TDFS1F-3960Z-10A	3960.0	Fo ± 792	1.80	2.00	40, 30 (Fo – 1460, Fo + 1190)	8.5 × 3.5 × 1.9	UWB	2000
TDFS1F-4050Z-10A-01	4050.0	Fo ± 750	1.80	2.00	40,30 (Fo – 1550, Fo + 1100)	8.5 × 3.4 × 1.9	UWB	2000
TDFM2A-4995X-10A-01	4995.0	Fo ± 95.5	1.50	2.00	20 (Fo – 795)	4.5 × 3.3 × 2.25	5G-LAN	2000
TDFM2C-4995X-10A	4995.0	Fo ± 95.5	3.10	2.00	35, 50 (Fo – 560, Fo + 560)	9.0 × 3.3 × 2.25	5G-LAN	2000
TDFS8A-5075Z-10A	5075.0	Fo ± 175.0	1.25	2.00	20 (4200)	3.75 × 3.25 × 1.8	5G-LAN	2000
TDFU2A-5125Z-10A	5125.0	Fo ± 100.0	1.30	2.00	35 (3800)	2.4 × 2.15 × 1.25	5G-LAN	3000
TDFM2A-5250X-10A	5250.0	Fo ± 100.0	1.50	2.00	20 (Fo – 800)	4.5 × 3.2 × 2.25	5G-LAN	2000
TDFM2C-5250X-10A	5250.0	Fo ± 100.0	3.00	2.00	35 (Fo – 400)	9.0 × 3.1 × 2.25	5G-LAN	2000
TDFS8A-5250X-10A	5250.0	Fo ± 100.0	1.50	2.00	20 (Fo – 800)	3.2 × 3.2 × 1.8	5G-LAN	2000
TDFU2A-5250X-10A	5250.0	Fo ± 100.0	1.30	2.00	30 (Fo – 1710)	2.4 × 2.1 × 1.25	5G-LAN	3000
TDFS8B-5375Z-10A	5375.0	Fo ± 475.0	1.20	2.00	22 (Fo – 1475, Fo + 2025)	4.5 × 3.0 × 1.7	5G-LAN	2000
TDFS8A-5437Z-10A	5437.5	Fo ± 287.5	1.20	2.00	25 (Fo – 1937)	3.2 × 3.05 × 1.7	5G-LAN	2000
TDFS8A-5500Z-10A	5500.0	Fo ± 350.0	1.00	2.00	25 (3500)	3.2 × 3.05 × 1.8	5G-LAN	2000
TDFM2A-5775T-10A-01	5775.0	Fo ± 50.0	3.30	2.70	28 (5225.0~5325.0)	4.5 × 2.9 × 2.25	5G-LAN	2000
TDFM2A-5775V-11A	5775.0	Fo ± 75.0	1.50	2.00	7 (Fo – 425)	4.5 × 2.9 × 2.25	5G-LAN	2000

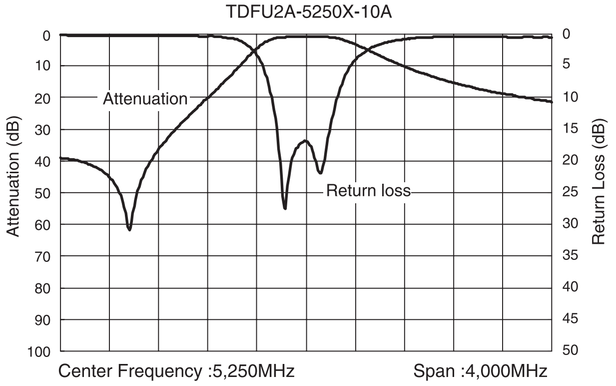
输入/输出阻抗：50Ω / Input Output impedance : 50Ω

产品示例
TDFU2A-5250X-10A

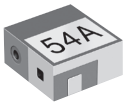


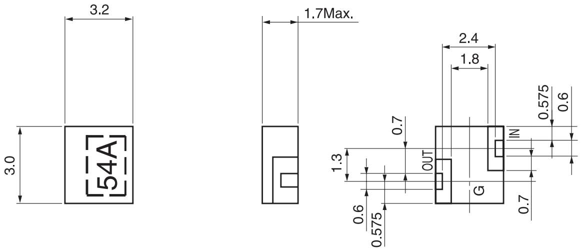
(Unit:mm)

Typical Characteristics / 典型特性



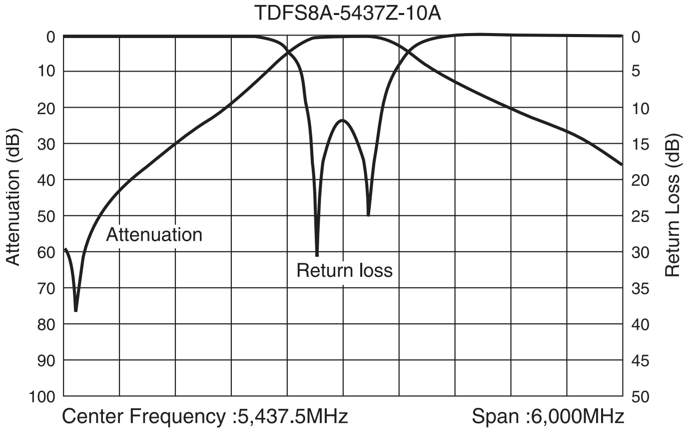
产品示例
TDFS8A-5437Z-10A



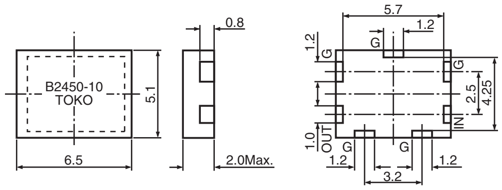


(Unit: mm)

Typical Characteristics / 典型特性

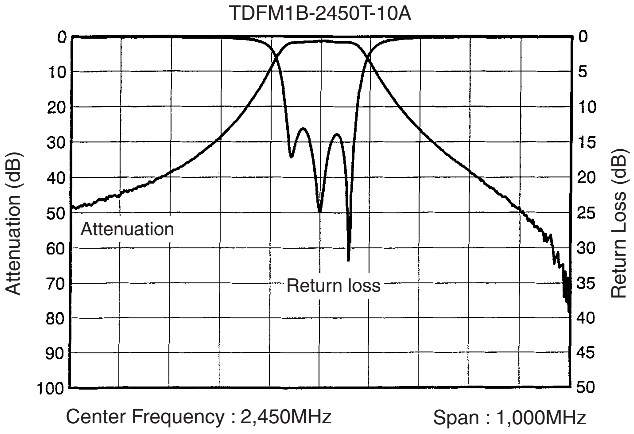


产品示例
TDFM1B-2450T-10A

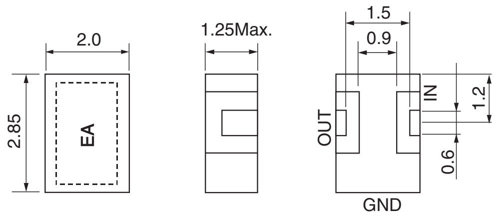


(Unit: mm)

Typical Characteristics / 典型特性

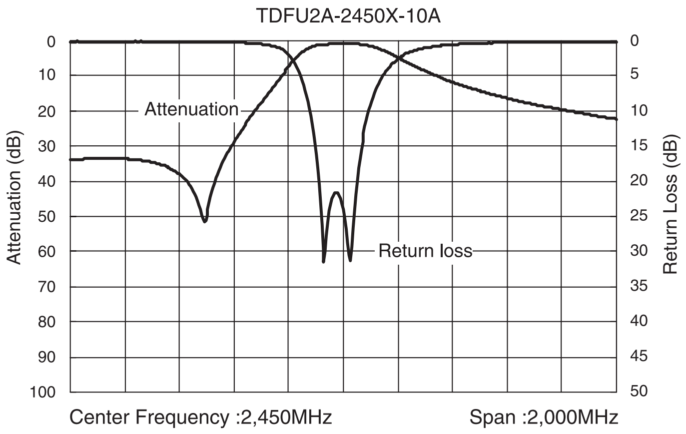


产品示例
TDFU2A-2450T-10A



(Unit: mm)

Typical Characteristics / 典型特性

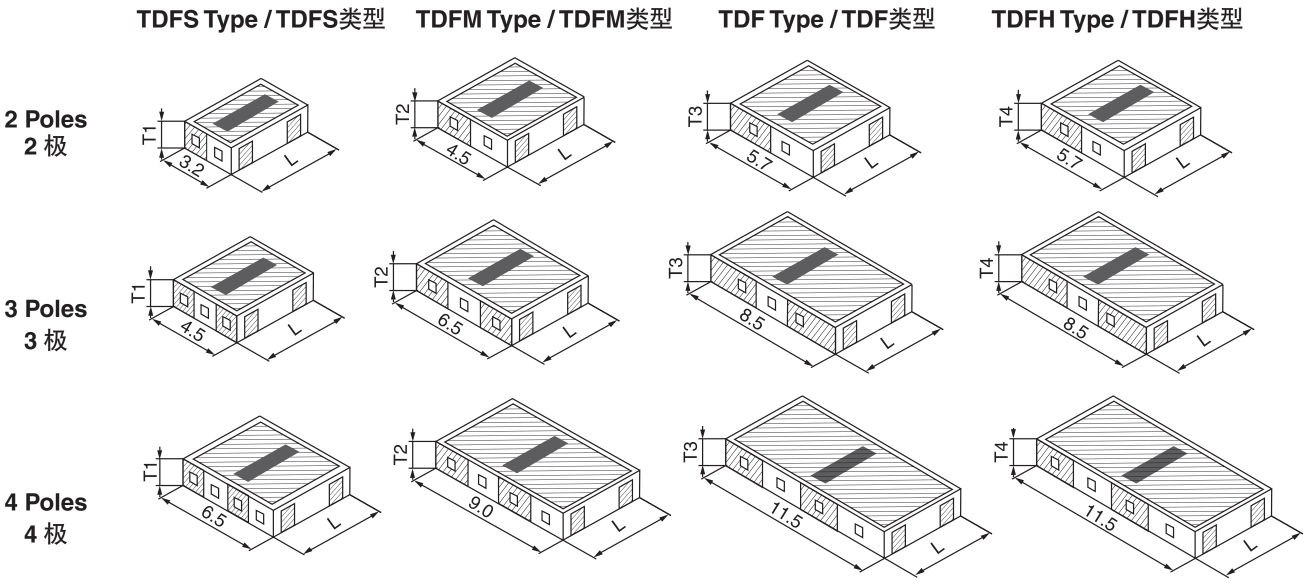


■PART NUMBERING SYSTEM / 部品编号

TDFM 3 A — 1907 E — 10 A P

- Taping / 卷带
- Solder Plate Less / 焊剂板材
- Specification Code / 规格编码
- Bandwidth Code / 带宽编码
- Center Frequency / 中心频率
- #Poles / #极（A=2, B=3, C=4）
- Profile Code / 厚度编码
- TOKO's Type Name / 东光株式会社型号名称

■DIMENSIONS / 尺寸



unit:mm

T1	T2	T3	T4
2.25 Max.	2.8 Max.	3.0 Max.	5.5 Max.
2.0 Max.	2.25 Max.	2.25 Max.	4.0 Max.
1.8 Max.	2.0 Max.	2.0 Max.	

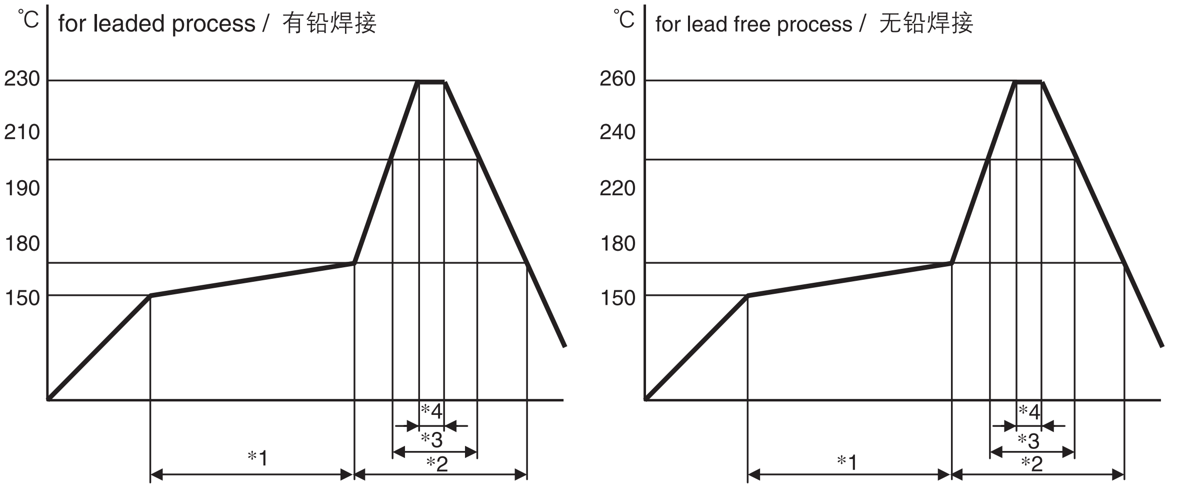
- The length, L, is different depending on the part number.
  Refer to the separate table.
  长度L因部品号不同而不同。
  请参见单独列表。

- For the details of shapes regarding individual part numbers, contact us separately.
  个别部品号的详细形状，请联系我们。

■PRECAUTIONS AND RECOMMENDED SOLDERING CONDITIONS FOR USING DIELECTRIC FILTERS SURFACE MOUNT TYPE

表面贴装型介质滤波器的使用注意事项和推荐焊接条件

Temperature profile (land seface temperature)
温度厚度（地表温度）



Pre-heat conditions
*1：150～160℃　60s. Max.

Reflow conditions
*2：160℃ Min.　45s. Max.
*3：200℃ Min.　30s. Max.
*4：230±5℃　5s. Max.

预热条件
*1：150～160℃　60秒以内

回流条件
*2：160℃以上　45秒以内
*3：200℃以上　30秒以内
*4：230±5℃　5秒以内

Pre-heat conditions
*1：150～180℃　120s. Max.

Reflow conditions
*2：180℃ Min.　150s. Max.
*3：230℃ Min.　40s. Max.
*4：255±5℃　5s. Max.

预热条件
*1：150～180℃　120秒以内

回流条件
*2：180℃以上　150秒以内
*3：230℃以上　40秒以内
*4：255±5℃　5秒以内

1. Reflow solder conditions
- Solderability
  When flux-mounted terminals are immersed in solder at following conditions, at least 95% of the surface should be covered by solder.
  Conditions
  leaded process : 230±5°C for 3±0.5 seconds
  lead free process : 260±5°C for 3±0.5 seconds
- Solder heat resistance
  No abnomalities under solder conditions of
  leaded process : 230±5°C for 5 seconds
  lead free process : 260±5°C for 5 seconds

2. Rinsing
   After Soldering, you should rinsing away the excess flux. Any commercially available rinsing agent may be used.
3. Other Precautions
   Perform soldering at as low a temperature as possible and for as short a time as possible.
   Make sure that the silver electrode of resonators is not covered by solder.
   Avoid applying external forces to terminals such as by bending or cutting them.
4. Iron Soldering
   Perform iron soldering with iron at following conditions.
   Conditions
   leaded process : 350±5°C for 5s. Max.
   lead free process : 390±5°C for 5s. Max.

1. 回流焊接条件
- 可焊性
  焊装的端子在以下条件下浸入焊剂时，至少95% 的表面应被焊剂覆盖。
  条件
  有铅焊接　:　230±5°C下3±0.5秒
  无铅焊接　:　245±5°C下3±0.5秒
- 焊剂耐热性
  在以下焊料条件下无异常:
  有铅焊接　:　230±5°C下秒
  无铅焊接　:　260±5°C下5秒

2. 清除
   焊接后，应清除多余的焊剂。
   可使用市面上可买到的任意一款水洗剂。
3. 其他注意事项
   在尽可能低的温度下用尽可能少的时间进行焊接操作。
   确保振荡器的银质电极没有被焊剂覆盖。
   避免对端子施加其他力量，如弯曲或切割等。
4. 烙铁焊接
   当烙铁处于以下状态时进行烙铁焊接操作。
   条件
   有铅焊接　:　350±5°C下最多5秒
   无铅焊接　:　390±5°C下最多5秒